200Gb/s QSFP-DD LR4 10km Transceiver

LA-OT-200G-LR4

Description

This product is a 200Gb/s transceiver module designed for 10km optical communication applications. The design is compliant to IEEE802.3bs 200GBASE-LR4 standard. For 200GAUI-8 Electrical interface, the module converts 8 input channels(ch) of 25Gb/s electrical data to 4 channels of LWDM optical signals, and multiplexes them into a single channel for 200Gb/s (PAM4) optical transmission. Reversely, on the receiver side, the module optically de-multiplexes a 200Gb/s(PAM4) input into 4 LWDM channels of signals, and converts them to 8 channels output electrical data. For 200GAUI-4 Electrical interface, the module converts 4 input channels(ch) of 50Gb/s electrical data to 4 channels of LWDM optical signals, and multiplexes them into a single channel for 200Gb/s (PAM4) optical transmission. Reversely, on the receiver side, the module optically de-multiplexes a 200Gb/s(PAM4) input into 4 LWDM channels of signals, and converts them to 8 channels output electrical data. For 200GAUI-4 Electrical interface, the module converts 4 input channels(ch) of 50Gb/s electrical data to 4 channels of LWDM optical signals, and multiplexes them into a single channel for 200Gb/s (PAM4) optical transmission. Reversely, on the receiver side, the module optically de-multiplexes a 200Gb/s(PAM4) input into 4 LWDM channels of signals, and converts them to 4 channels output electrical data. The central wavelengths of the 4 LWDM channels of signals, and converts them to 4 channels output electrical data. The central wavelengths of the 4 LWDM channels. It contains a duplex LC connector for the optical interface and a 76-pin connector for the electrical interface. To minimize the optical dispersion in the long-haul system, single-mode fiber (SMF) has to be applied in this module. Host FEC is required to support up to 10km fiber transmission. The product is designed with form factor, optical/electrical connection and digital diagnostic interface according to the QSFP-DD Multi-Source Agreement (MSA). It has been designed to meet the harshest external

Features

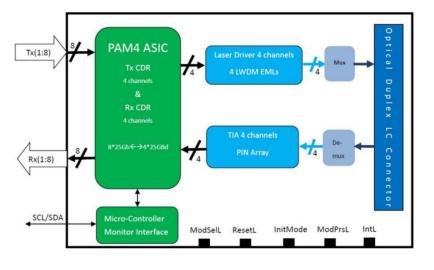
- IEEE802.3bs compliant
- QSFP-DD MSA compliant
- 4 LWDM lanes MUX/DEMUX design
- Supports 212.5Gb/s aggregate bit rate
- Up to 10km transmission on single mode fiber (SMF) with FEC
- Operating case temperature: 0 to 70oC
- 200GAUI-8 and 200GAUI-4 electrical interface
- Maximum power consumption 10.8W
- LC duplex connector
- RoHS compliant

Applications

- Data Center Interconnect
- 200G Ethernet
- Enterprise networking

Transceiver Block Diagram

For 200GAUI-8



For 200GAUI-4

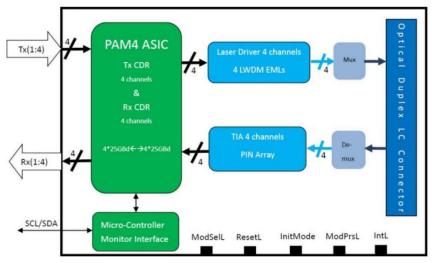


Figure 1. Transceiver Block Diagram

Pin Assignment and Description

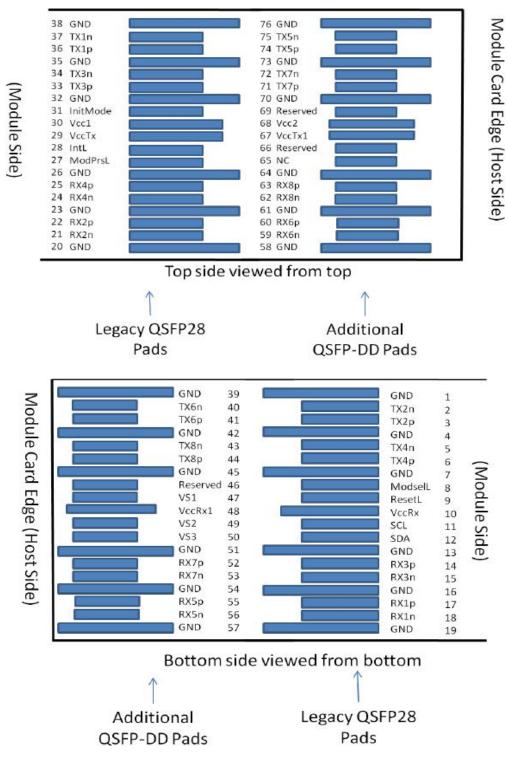


Figure 2. MSA compliant Connector

Pin Definition

Pin	Logic	Symbol	Description	Plug Sequence	Notes
1		GND	Ground	1B	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3B	
3	CML-I	Тх2р	Transmitter Non-Inverted Data Input	3B	
4		GND	Ground	1B	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3B	
6	CML-I	Тх4р	Transmitter Non-Inverted Data Input	3B	
7		GND	Ground	1B	1
8	LVTTL-I	ModSelL	Module Select	3B	
9	LVTTL-I	ResetL	Module Reset	3B	
10		VccRx	+3.3V Power Supply Receiver	2B	2
11	LVCMOS-	SCL	2-wire serial interface clock	3B	
	I/O				
12	LVCMOS-	SDA	2-wire serial interface data	3B	
	I/O				
13		GND	Ground	1B	1
14	CML-0	Rx3р	Receiver Non-Inverted Data Output	3B	
15	CML-O	Rx3n	Receiver Inverted Data Output	3B	
16	GND	Ground	18		1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3B	
18	CML-O	Rx1n	Receiver Inverted Data Output	3В	
19		GND	Ground	1B	1
20		GND	Ground	1B	1
21	CML-0	Rx2n	Receiver Inverted Data Output	3B	
22	CML-0	Rx2p	Receiver Non-Inverted Data Output	3B	
23		GND	Ground	1B	1
24	CML-0	Rx4n	Receiver Inverted Data Output	3B	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3B	
26		GND	Ground	18	1
27	LVTTL-O	ModPrsL	Module Present	3B	
28	LVTTL-O	IntL	Interrupt	3B	

29		VccTx	+3.3V Power supply transmitter	2B	2
30		Vcc1	+3.3V Power supply	2B	2
31	LVTTL-I	InitMode	Initialization mode; In legacy QSFP	3B	
			applications, the InitMode pad is		
			called LPMODE		
32		GND	Ground	1B	1
33	CML-I	Тх3р	Transmitter Non-Inverted Data Input	3B	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3B	
35		GND	Ground	1B	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3B	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3B	
38		GND	Ground	1B	1
39		GND	Ground	1A	1
40	CML-I	Tx6n	Transmitter Inverted Data Input	3A	
41	CML-I	Тх6р	Transmitter Non-Inverted Data Input	3A	
42		GND	Ground	1A	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	3A	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	3A	
45		GND	Ground	1A	1
46		Reserved	For future use	3A	3
47		VS1	Module Vendor Specific 1	3A	3
48		VccRx1	3.3V Power Supply	2A	2
49		VS2	Module Vendor Specific 2	3A	3
50		VS3	Module Vendor Specific 3	3A	3
51		GND	Ground	1A	1
52	CML-0	Rx7p	Receiver Non-Inverted Data Output	3A	
53	CML-O	Rx7n	Receiver Inverted Data Output	3A	
54		GND	Ground	1A	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	3A	
56	CML-0	Rx5n	Receiver Inverted Data Output	3A	
57		GND	Ground	1A	1
58		GND	Ground	1A	1

59	CML-O	Rx6n	Receiver Inverted Data Output	3A	
60	CML-0	Rx6p	Receiver Non-Inverted Data Output	3A	
61		GND	Ground	1A	1
62	CML-0	Rx8n	Receiver Inverted Data Output	3A	
63	CML-0	Rx8p	Receiver Non-Inverted Data Output	3A	
64		GND	Ground	1A	1
65		NC	No Connect	3A	3
66		Reserved	For future use	3A	3
67		VccTx1	3.3V Power Supply	2A	2
68		Vcc2	3.3V Power Supply	2A	2
69		Reserved	For Future Use	3A	3
70		GND	Ground	1A	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	3A	
72	CML-I	Tx7n	Transmitter Inverted Data Input	3A	
73		GND	Ground	1A	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	3A	
75	CML-I	Tx5n	Transmitter Inverted Data Input	3A	
76		GND	Ground	1A	1

Notes:

1. GND is the symbol for signal and supply (power) common for QSFP-DD modules. All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane.

2. VccRx, Vcc1 and VccTx are the receiving and transmission power suppliers and shall be applied concurrently. Recommended host board power supply filtering is shown in Figure 3 below. Vcc Rx, Vcc1 and Vcc Tx may be internally connected within the QSFP-DD transceiver module in any combination. The connector pins are each rated for a maximum current of 1000mA.

Recommended Power Supply Filter

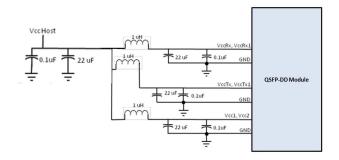


Figure 3. Recommended Power Supply Filter

Absolute Maximum Ratings

It has to be noted that the operation in excess of any individual absolute maximum ratings mightcause permanent

damage to this module.

Parameter	Symbol	Min	Max	Units	Notes
Storage Temperature	TS	-40	85	degC	
Operating Case Temperature	ТОР	0	70	degC	
Power Supply Voltage	VCC	-0.5	3.6	V	
Relative Humidity (non-condensation)	RH	0	85	%	
Damage Threshold, each Lane	THd	3.5		dBm	

Recommended Operating Conditions and Power Supply Requirements

Parameter	Symbol	Min	Typical	Max	Units	Notes
Operating Case Temperature	ТОР	0		70	degC	
Power Supply Voltage	VCC	3.135	3.3	3.465	V	
Data Rate, each Lane			26.5625		GBd	
			53.125		Gb/s	
Data Rate Accuracy		-100		100	ppm	
Pre-FEC Bit Error Ratio				2.4x10 ⁻		
				4		
Post-FEC Bit Error Ratio				1x10-12		1
Control Input Voltage High		2		Vcc	V	
Control Input Voltage Low		0		0.8	V	
Link Distance with G.652	D	0.002		10	km	2

Notes:

1. FEC provided by host system.

2. FEC required on host system to support maximum distance.

Electrical Characteristics

The following electrical characteristics are defined over the Recommended Operating Environment unless otherwise specified.

200GAUI-8 Electrical Characteristics

Parameter	Symbol	Min	Typical	Max	Units	Notes
Power Consumption				10.8	W	
Supply Current	lcc			3258	mA	
		Transmit	ter (each Lane)		1	
Signaling rate per lane(200GBASE-LR4)		26.5	625±100ppm		GBd	
Peak-to-peak differential				900	mv	
output voltage						
AC common-mode		17.5	mV RMS with to signal gr	-	mV	
output voltage		Mee	ts Equation (12			
Differential output returnloss		Wiee	constrai			
Reference impedance for output return loss			100		Ω	
Common to differential mode conversion	Zin	Mee	ts Equation (8) constrain	-		
Differential termination mismatch			Less than	10%		
Transition time		Greate	r than or equal	to 12ps		
Eye width			0.57		UI	
Eye height			228		mV	
Crosstalk source		Patter	nous crosstalk : n 5, Pattern 3, 00GBASE-R sig	or valid		
Vertical eye closure				5.5	dB	
	Receive	r (each Lane))			
Single-ended Output Voltage		-0.4 3.3		v	Referredto signal common	
Differential pk-pk input voltage tolerance	_	900			mV	
יטונמצב נטובומווכב		Equati				

Differential input return	on				
loss	(83E-	-			
	5)	-			
	Equati				
Differential to common-	on	-			
mode input returnloss	(83E-				
	6)	-			
Termination Mismatch at					
1MHz			10	%	
Module stressed input		1	I		
test	See 83E.3.4.1			-	
DC common mode					
voltage	-350		2850	mv	
Eye width		0.46		UI	
Eye height		95		mV	

200GAUI-4 Electrical Characteristics

Parameter	Symbol	Min	Typical	Мах	Units	Notes
Power Consumption				10.8	W	
Supply Current	lcc			3258	mA	
Transmitter (each Lane)				I	<u> </u>	
Signaling rate per lane(200GBASE-LR4)			10.8		GBd	
Peak-to-peak differential output voltage				900	mv	
AC common-mode output voltage				17.5	mV	
Differential output return loss			Equation (83E-2	2)		

Common to differential mode conversion	Zin	Equation (83E–3)					
Differential termination mismatch					10	%	
Transition time (20% to 80%)		9.5				ps	
DC common mode voltage		-350			2850	mV	
Receiver (each Lane)							
Single-ended Output Voltage		-0.4			3.3	v	Referred to signal common
Differential pk-pk input voltage tolerance		900				mV	
Differential input return loss		Equati on (83E– 5)					
Differential to common- mode input returnloss		Equati on (83E–					

Optical Characteristics

Parameter	Symbol	Min	Typical	Max	Units	Notes
	LO	1294.53	1295.56	1296.59	nm	
Wavelength Assignment	L1	1299.02	1300.05	1301.09	nm	
	L2	1303.54	1304.58	1305.63	nm	
	L3	1308.09	1309.14	1310.19	nm	
		Transr	nitter			
Data Rate, each Lane		26.56	525 ± 100 pj	om	GBd	
Modulation Format			PAM4			
Side-mode Suppression Ratio	SMSR	30			dB	Modulated
Total Average Launch Power	РТ			11.3	dBm	
Average Launch Power, each	PAVG	-3.4		5.3	dBm	1
Lane		5.4		5.5	abiii	-
Outer Optical Modulation						
Amplitude (OMA _{outer}), each	РОМА	-0.4		5.1	dBm	2
Lane						
		-1.8			dB	For ER
Launch Power in OMAouter						≥4.5dB
minus TDECQ, each Lane		-1.7			dB	For ER <4.5dB
Transmitter and Dispersion Eye	TDECQ			3.4	dB	
Clouser for PAM4, each Lane	TDECQ			5.4	ub	
Extinction Ratio	ER	3.5			dB	
Difference in Launch Power						
between any Two Lanes				4	dB	
(OMA _{outer})						
RIN16.50MA	RIN			-132	dB/Hz	
Optical Return Loss Tolerance	TOL			15.1	dB	

Transmitter Reflectance	TR			-26	dB	
Average Launch Power of OFF	Poff			-30	dBm	
Transmitter, each Lane						
		Rec	eiver		<u> </u>	
Data Rate, each Lane		26.5625	±GBd			
		100 ppm				
Modulation Format		PAM4				
Damage Threshold, each Lane	THd	6.3			dBm	3
Average Receive Power, eachLane		-9.7		5.3	dBm	4
Receive Power (OMA _{outer}), each				5.1	dBm	
Lane						
Difference in Receiver Power						
between any Two Lanes				4.2	dB	
(OMA _{outer})						
Receiver Sensitivity	SEN			-7.7	dBm	For BER
(OMAouter),each Lane						of 2.4E-4
Stressed Receiver Sensitivity	SRS				dBm	5
(OMA _{outer}), each Lane				-5.2		
Receiver Reflectance	RR			-26	dB	
LOS Assert	LOSA				dBm	
		-25.7				
LOS De-assert	LOSD			-11.7	dBm	
LOS Hysteresis	LOSH	0.5			dB	

Stressed Conditions for Stress Receiver Sensitivity (Note 6)								
Stressed Eye Closure for PAM4			3.4	dB				
(SECQ), Lane under Test								
OMAouter of each AggressorLane		-1		dBm				
Notoo								

Notes:

1. Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.

2. Even if the TDECQ < 1.4 dB for an extinction ratio of \geq 4.5 dB or TDECQ < 1.3 dB for an extinction ratio of < 4.5 dB, the OMAouter (min) must exceed the minimum value specified here.

The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level.

3. Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.

4. Measured with conformance test signal for BER = 2.4x10-4.

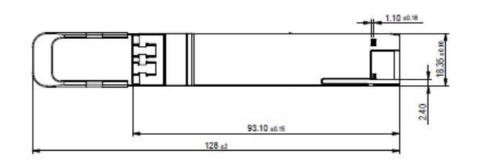
5. These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

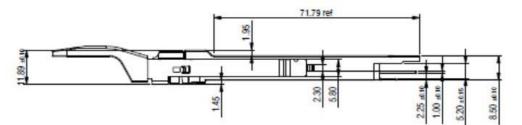
Digital Diagnostic Functions

The following digital diagnostic characteristics are defined over the normal operating conditions unless otherwise specified.

Parameter	Symbol	Min	Max	Units	Notes
Temperature monitors absolute error	DMI_Temp	-3	3	degC	Over operating temperature range
Supply voltage monitor absolute error	DMI_VCC	-0.1	0.1	V	Over full operating range
Channel RX power monitor absolute error	DMI_RX_Ch	-3	3	dB	
Channel Bias current monitor	DMI_Ibias_Ch	-10%	10%	mA	
Channel TX power monitor absolute error	DMI_TX_Ch	-3	3	dB	

Outline Drawing (mm)









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